

F

E

D

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A

RoHS Compliant

SYMBOL

REV.

REVISION

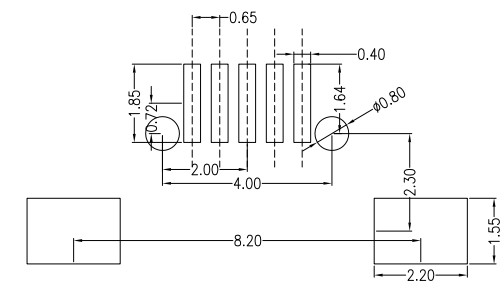
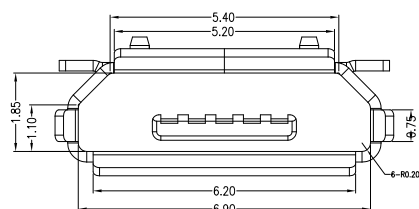
APPROVAL

DATE

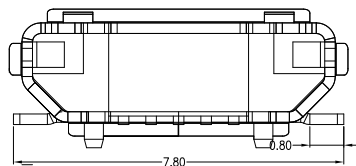
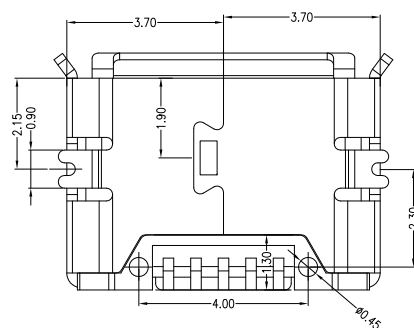
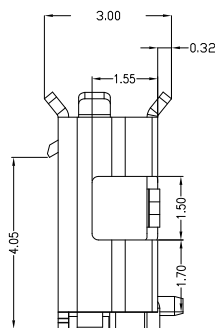
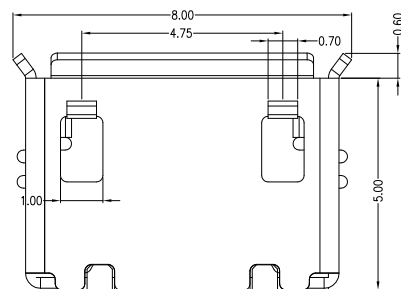
新版圖紙

Winky

2011/07/21



PCB LAYOUT



Material:

1.1 Housing: High Temperature

thermoplastic with G.F, UL94V-0

1.2 Contact: copper alloy, $t=0.20\text{mm}$

1.3 Shell: copper alloy, $t=0.25\text{mm}$

2. Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding
voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kg Max.

2.6 Total unlatching force: 1.0 Kg Min. 0.81~2.05

Kg Min. after 10000 insertion/extraction cycles

2.7 Temperature range: -30°C~80°C

Ordering Information:

DU03-MSE B x 05RLQ

① ②

(1). Color: B: BLACK

(2). Contact Plating:

0: Selective Gold Flash over 30u" nickel plated
on contact area

4: Selective 15u" Gold over 50u" nickel plated
on contact area

5: Selective 30u" Gold over 50u" nickel plated
on contact area

DST-conn Tech. Co., Ltd.

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PART NAME

MICRO-USB-5P-SMT

DRAWING

Winky

DWG. No.

DU03

PART NO.

DU03-MSEBx05RLQ

CHECK

Roy

REV.

A



UNIT :

mm

TOLERANCE UNLESS
OTHERWISE SPECIFIED

X.X ± 0.30
X.XX ± 0.15
X.XXX

ANGLE

±2°

APPROVAL

John

DATE

2011/07/21

SCALE

1:1

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